

SPECIFICATION

• Supplier : Samsung electro-mechanics • Part Number : CL10C040BB8ANNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 4pF, 50V, ±0.1pF, C0G, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>040</u> <u>B</u> <u>B</u> <u>8</u> <u>A</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor						
2	Size	0603 (inch code)	L: 1.6	± 0.1 mm	W:	8.0	± 0.1	mm
3	Dielectric	C0G	8	Inner electrode		Pd		
4	Capacitance	4 pF		Termination		Ag		
⑤	Capacitance	±0.1 pF		Plating		Sn 100)%	(Pb Free)
	tolerance		9	Product		Norma	ıl	
6	Rated Voltage	50 V	10	Special		Reserv	ved for	future use
7	Thickness	0.8 ± 0.1 mr	m 11	Packaging		Cardbo	oard T	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	480 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	COG						
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder					
	is to be soldered newly	235±5℃, 5±0.5sec.					
		2) SnAg3.0Cu0.5 solder					
		245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to Capacitance change :		Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within ±2.5% or ±0.25pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)				
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)				
Humidity	Capacitance change :	40±2℃, 90~95%RH, 500+12/-0hrs				
	within ±5% or ±0.5pF whichever is larger					
	Q: 240 min					
	IR : 1000Mohm or 50Mohm · μF					
	Whichever is Smaller					
Moisture	Capacitance change :	With rated voltage				
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q: 113.33 min					
	IR: 500Mohm or 25Mohm $\cdot \mu$ F					
	Whichever is Smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature				
	Q: 240 min	1000+48/-0hrs				
	IR: 1000Mohm or 50Mohm $\cdot \mu$ F					
	Whichever is Smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25 °C				
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$ C				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\mathrm{C}$, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.